Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, Dan Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A0702-01** DATE: **22-Mar-2007**

Product Affected: 24.5mm x 19.5mm FCBGA-655
Refer to attachment II for the
affected part numbers.

Date Effective: **22-Jun-2007**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ☒ Other

Assembly lot marked on the device provides traceability to the mold compound type

Contact: Geoffrey Cortes
Title: Product Quality
Phone #: (408) 284-8321
Fax #: (408) 284-1450
E-mail: Geoffrey.Cortes@idt.com

Attachment: ☒ Yes ☐ No

Samples: Please contact your local sales representative for sample request & availability.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☒ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise our customers that IDT is converting underfill material from Sumitomo 4152RA to Namics U8437-2 after successful qualification. There is no change to the moisture performance of these packages.

Please see attachment for qualification data and affected part number list.

RELIABILITY/QUALIFICATION SUMMARY:

There is no impact with regards to the package performance or reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

ATTACHMENT I - PCN #: A0702-01

PCN Type: Assembly Material Change

Data Sheet Change: None

Detail Of Change: This notification is to advise our customers that IDT is converting underfill material from Sumitomo 4152RA to Namics U8437-2 after successful qualification.

There is no change in the moisture sensitivity level (MSL).

Please see attachment I for qualification data and attachment II for affected part number list.

Description	Affected Package Types	Material	
		Old	New
Underfill Material	24.5mm x 19.5mm FCBGA-655	Sumitomo 4152RA	Namics U8437-2

Sample Availability: Samples are not built ahead of the change and are limited to selective devices. Please contact your local IDT sales representative for sample request and availability.

ATTACHMENT I - PCN #: A0702-01

Qualification Plan #: **P06-06-05R1**

Test Vehicle: **24.5mm x 19.5mm FCBGA-655 (1 lot)**

Qualification Test Plan and Results:

Test Description	Test Method (Latest specs in effect)	Number of Lot	Test Results (SS/Rej)
* Temperature Cycling (Cond B, 1000 cycles)	JESD22-A104	1	45/0
* Unbiased HAST (130°C, 85% RH, 100 hours)	JESD22-A118	1	45/0
High Temperature Stabilization Bake (150 °C, 1000 hours)	JESD22-A103	1	77/0
Moisture Sensitivity Classification, L4	J-STD-020	1	45/0

Note: * Test require moisture pre-conditioning sequence per JESD22-A113.

ATTACHMENT II - PCN #: A0702-01

Affected Part Number

IDT Part Number	IDT Part Number	IDT Part Number	IDT Part Number
IDTAMB0480A3RH	IDTAMB0480ARH	IDTAMB0481A0RH	IDTAMB0482C1RH
IDTAMB0480A3RJ	IDTAMB0480ARJ	IDTAMB0481A0RJ	IDTAMB0482C1RJ
IDTAMB0480A5RH	IDTAMB0480B1RH	IDTAMB0481A1RJ	
IDTAMB0480A5RJ	IDTAMB0480B1RJ	IDTAMB0482C0RJ	

Notes: For T & R (shipping method) "8" is added to the p/n.